



ZL MOSFET

ZL010N07GH

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
100V	6.9mΩ@10V	80A

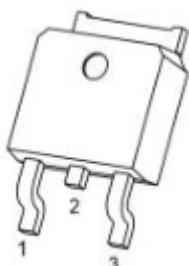
## Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

## Application

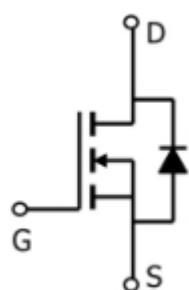
- Power switching application
- PWM Application
- DC-DC Converter

## Package



TO-252(1:G 2:D 3:S)

## Circuit diagram

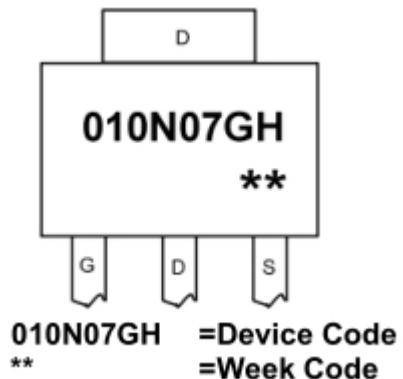




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## Marking



## Absolute maximum ratings

( $T_a=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_c = 25^\circ\text{C}$ )	$I_D$	80	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	320	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	306	mJ
Power Dissipation( $T_c = 25^\circ\text{C}$ )	$P_D$	120	W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	0.96	$^\circ\text{C}/\text{W}$
Storage Temperature Range	$T_{STG}$	-55~ +150	$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-55~ +150	$^\circ\text{C}$



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## Electrical characteristics

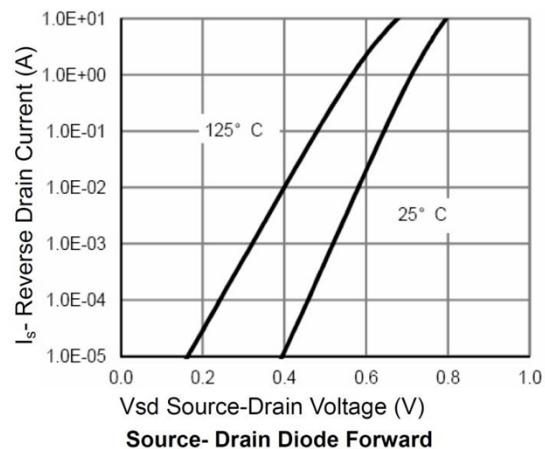
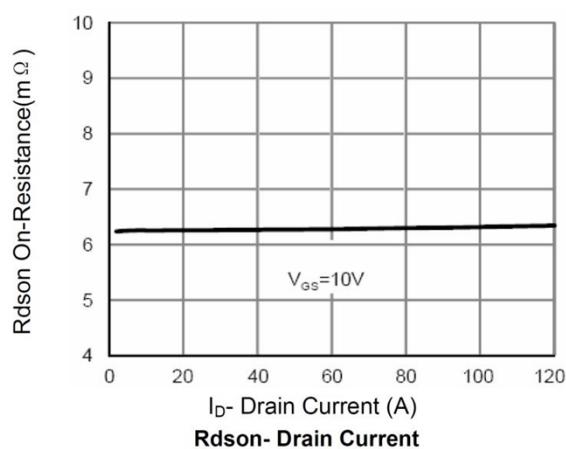
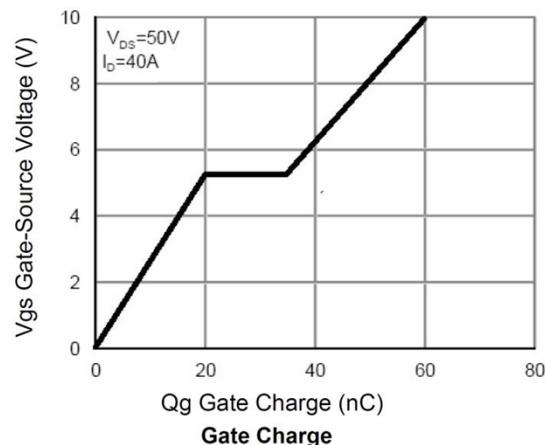
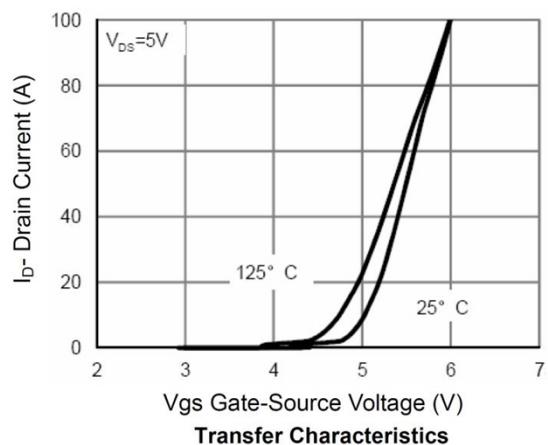
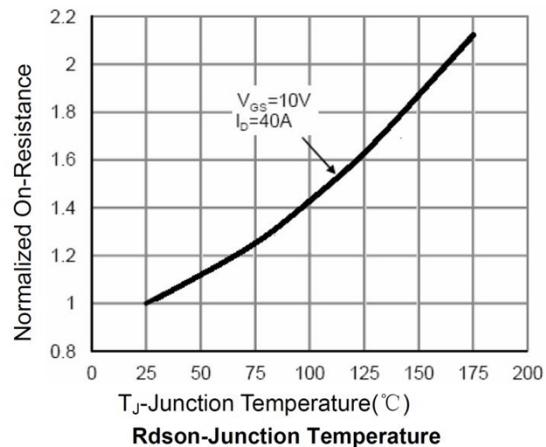
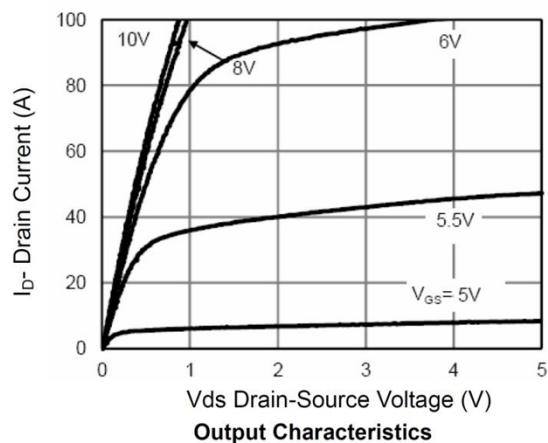
(T<sub>A</sub>=25°C, unless otherwise noted)

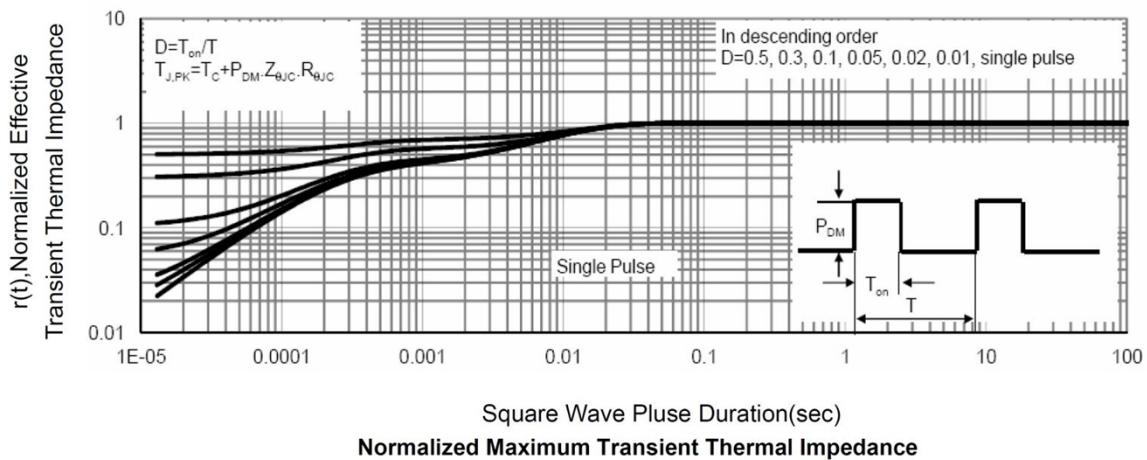
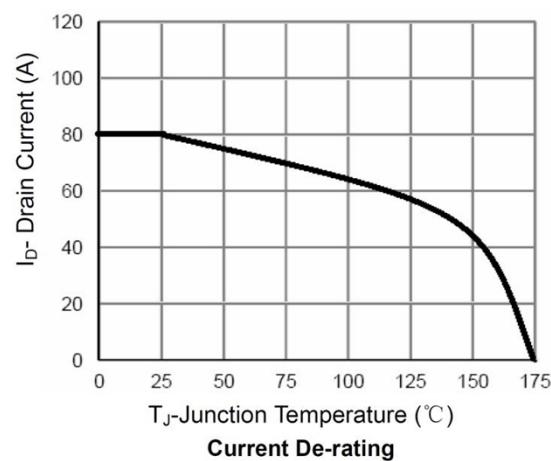
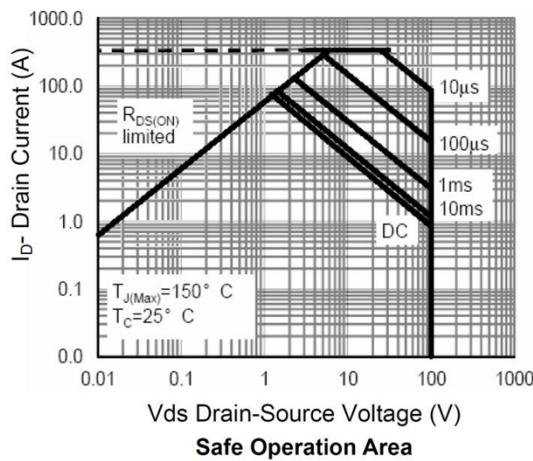
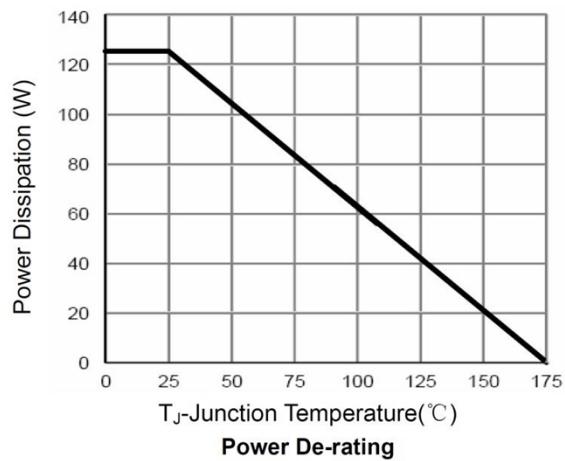
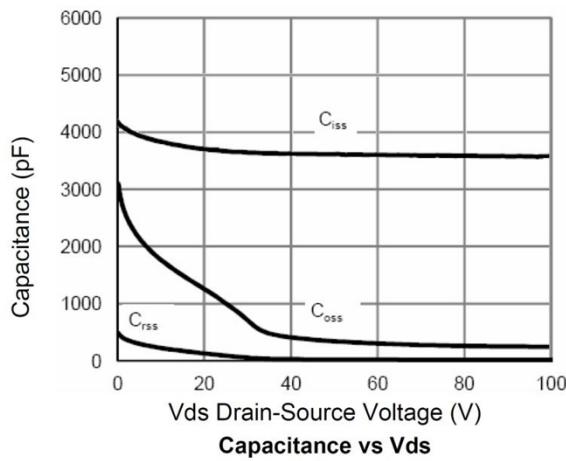
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	100			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C			1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	uA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	3	4	V
Static Drain-Source on-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A		6.9	8.7	mΩ
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1MHz		2335		pF
Output Capacitance	C <sub>oss</sub>			330		
Reverse Transfer Capacitance	C <sub>rss</sub>			7		
<b>Switching Characteristics</b>						
Total Gate Charge (4.5V)	Q <sub>g</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A		35		nC
Gate-Source Charge	Q <sub>gs</sub>			5.5		
Gate-Drain Charge	Q <sub>gd</sub>			6		
Turn-On Delay Time	T <sub>d(on)</sub>	V <sub>DD</sub> = 50V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A, R <sub>G</sub> = 6Ω		8		nS
Rise Time	T <sub>r</sub>			13		
Turn-Off Delay Time	T <sub>d(off)</sub>			42		
Fall Time	T <sub>f</sub>			19		
<b>Drain-Source Body Diode Characteristics</b>						
Drain Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A, T <sub>J</sub> = 25°C			1.2	V

### Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub> = 50V, V<sub>GS</sub> = 10V, L = 0.5mH, R<sub>G</sub> = 25Ω
4. The power dissipation is limited by 150°C junction temperature

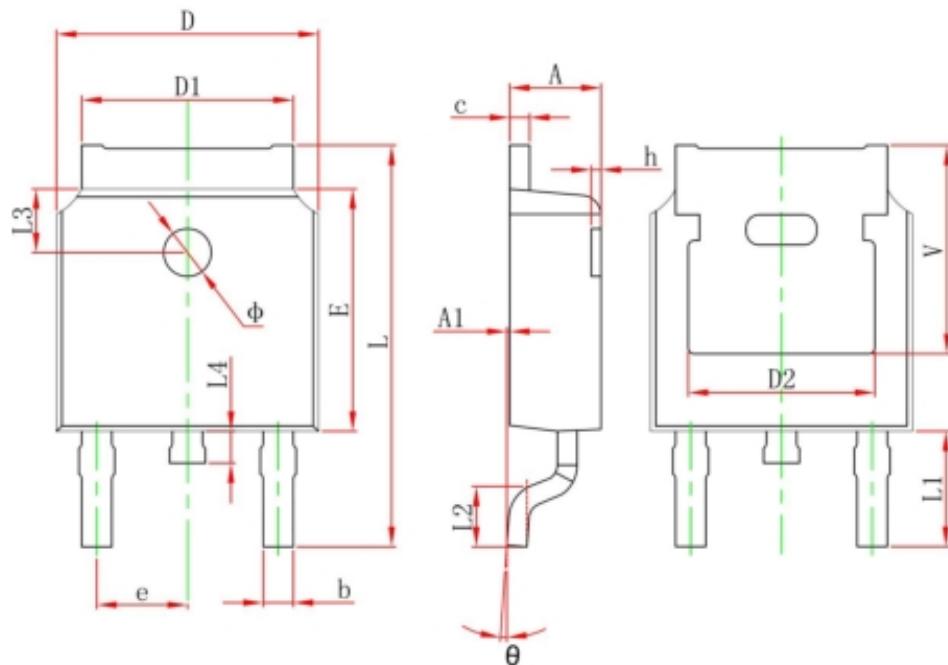
## Typical Characteristics







## TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	